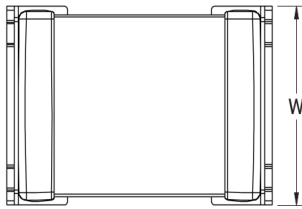


TOP VIEW
Single or Double Chip Stack



PROFILE VIEW
Single Chip Stack



Click [here](#) for the 3D model.

Dimensions

L	6mm +/-0.5mm
W	5mm +/-0.5mm
T	3.5mm +/-0.30mm
B	1.6mm +/-0.3mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	1300

General Information

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	410 mg
Chip Size	2220-1
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

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